



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**In re Application of:**

Vernon M. Williams

**Serial No.:** 09/652,503

**Filed:** August 31, 2000

**For:** TRANSFER MOLDING AND  
UNDERFILLING METHOD AND  
APPARATUS

**Confirmation No.:** 3679

**Examiner:** W. Brewster

**Group Art Unit:** 2823

**Attorney Docket No.:** 2269-4303US  
(99-0584.00/US)

**Notice of Allowance Mailed:**

December 3, 2003

NOTICE OF EXPRESS MAILING

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Commissioner for Patents  
P.O. Box 1450  
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Sir:

Please amend the above-referenced application as follows:

**Amendments to the Title** appear on page 3 of this paper.

**Amendments to the Specification** begin on page 4 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 7 of this paper.

**Remarks** begin on page 16 of this paper.

IN THE TITLE:

The title has been amended herein. Pursuant to 37 C.F.R. §§ 1.121 and 1.125 (as amended to date), please enter the title as amended.

**TRANSFER MOLDING AND UNDERFILLING METHOD AND APPARATUS  
INCLUDING ORIENTING THE ACTIVE SURFACE OF A  
SEMICONDUCTOR SUBSTRATE CHIP SUBSTANTIALLY VERTICALLY**